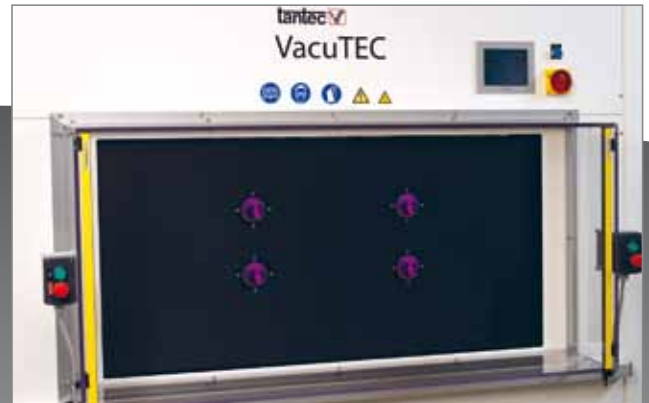


Product Information

VacuTEC - Vacuum Plasma Treater



Vacuum Plasma Treater, Model VacuTEC
Treaters integrated in automated production lines built by OEM's.



VacuTEC - Vacuum Plasma Treater

Standard and Customised Vacuum Plasma Treaters

Tantec's VacuTEC Plasma Treater is designed for treatment of a large number of different injection moulded parts. The VacuTEC is available with both single and multiple tray configuration. The VacuTEC offers very fast treatment times and optimum adhesion properties for downstream coating, gluing, painting and printing applications.

In the treating chamber a vacuum is built up to between 2 and 12 mbar before an electrical discharge is created through the integrated plasma electrode. Treatment cycle times are often short, between 2-120 seconds depending on the material and its formulation.

The VacuTEC is appreciated for its simplicity of operation, reliability in production and fast process speed. Treating gasses such as argon and oxygen can be applied, but in most

cases this is not necessary due to the high power exposed by the plasma discharge.

VacuTEC uses the advanced Tantec power generator HV-X series as power supply and specially designed plasma transformers to provide voltage to the plasma electrodes.

TECHNICAL DATA

Features:

- Easy to install and use
- Fast treatment times
- Standard or customised chambers
- Vacuum level
- Process gas
- Process control
- Cost efficient surface treatment
- Vacuum pressure Plasma
- Chamber doors

TechnicalData

Plasma & Corona Treaters

adhesion bonding coating
adhesion bonding coating
adhesion bonding coating
adhesion bonding coating

Features:

Easy to install and use

Connect to mains power and compressed air.

Fast treatment times

High power impact enables treatment times from 20-180 seconds, depending on material.

Standard or customised chambers

Chamber and part trays can be designed to most applications. Many available as standard.

Vacuum level

The plasma discharge is active from 1-12 mbar depending on application.

Process gas

Process gasses such as oxygen and argon can be used, but in most cases it is not necessary.

Process control

The entire plasma process is controlled by the HV-X generator and the PLC unit. All parameters are displayed through the touch panel. (Standard – Proface).

Cost efficient surface treatment

Due to the low power consumption and no need of special treatment gasses the unit is a very cost efficient solution for improving surface wettability and adhesion.

Vacuum pressure Plasma

Enables treatment of both conductive and non-conductive surfaces.

Chamber doors

Standard doors with manual opening or automatic motor driven doors available.

Technical Specifications	VacuTEC Vacuum Plasma Treater
Mains voltage and frequency	100-480 VAC 50/60 Hz
Output voltage/plasma power	Max. 400 Vp/max. 2000 Watt
Power supply	HV-X plasma generator series
Compressed air inlet	5-6 bar dry & clean
Process gas	Standard: air, oxygen, argon, nitrogen on request
Vacuum pump capacity in m ³ /min.	15 to 240 m ³ /min., depending on size of vacuum chamber, others on request
Vacuum level	1-12 mbar
Evacuation time, typical	15-60 seconds, depending on chamber size and pump capacity
Plasma treatment time, typical	20-180 seconds, depending on material
Control and connectivity	Complete with touch panel. (Standard - Proface)
Regulation compliance	CE - RoHS - WEEE

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